

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Todd O. Bolken

Serial No.: 10/791,192

Filed: March 2, 2004

For: TWO-STAGE TRANSFER MOLDING  
DEVICE TO ENCAPSULATE MMC  
MODULE

Confirmation No.: 1966

Examiner: D. Zarneke

Group Art Unit: 2891

Attorney Docket No.: 2269-4794.4US  
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Notice of Allowance Mailed:

May 1, 2007

**VIA ELECTRONIC FILING**  
July 25, 2007

**FEE ADDRESSEE FOR RECEIPT OF PTO NOTICES  
RELATING TO MAINTENANCE FEES**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

1. This letter is to specify that the FEE ADDRESSEE for this patent is:

MICRON TECHNOLOGY, INC.

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8000 South Federal Way  
Boise, Idaho 83707-0006

2. The Customer Number for the Fee Addressee is 26809.
3. Any prior FEE ADDRESSEE for this patent is hereby revoked.
4. It is certified that the person whose signature appears below has the authority to change the FEE ADDRESSEE for this patent.

Respectfully submitted,



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JRD/djp:lmh  
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